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Field III Text of the Abstract

A diode (10) is described, having a press-fit base (11) which has a fastening region (12), that extends axially, for a semiconductor chip (13) and having a head wire (17) fastened to the semiconductor chip. The head wire has a graded wire connector or rather a region (21) which, together with the press-fit base and a sleeve (22) forms a tight [leak-proof] housing. The hollow spaces that appear in the housing are filled up with sealing compound (23) for stabilization, the sealing compound (23) being only within the housing.